

MA110

Silicon Epitaxial Planar Type

Switching

■ Features

- High density mounting by "S-Mini type" package is possible.
- Fast t_{rr}
- Small C_i

■ Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Item	Symbol	Value	Unit
Reverse Voltage (DC)	V_R	40	V
Peak Reverse Voltage	V_{RM}	40	V
Average Forward Current	$I_{F(AV)}$	100	mA
Peak Forward Current	I_{FM}	225	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}^*	500	mA
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	$-55 \sim +150$	$^\circ\text{C}$

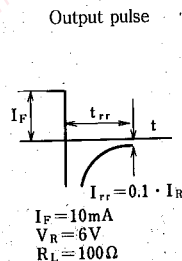
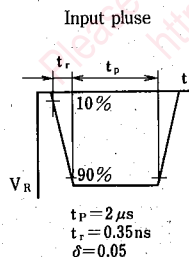
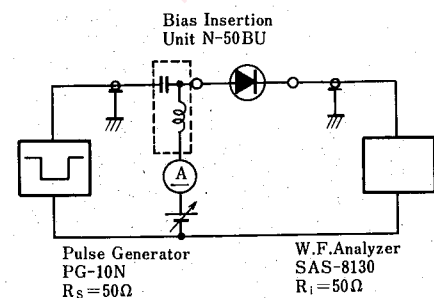
* $t=1s$

■ Electrical Characteristics ($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	min.	typ.	max.	Unit
Reverse Current (DC)	I_R	$V_R=35V$			100	nA
Forward Voltage (DC)	V_F	$I_F=100mA$		0.95	1.2	V
Reverse Voltage (DC)	V_R	$I_R=100\mu A$	40			V
Terminal Capacitance	C_i	$V_R=0, f=1MHz$		0.6	1.2	pF
Reverse Recovery Time	t_{rr}^*	$I_F=10mA, V_R=6V$ $I_{rr}=0.1 \cdot I_R, R_L=100\Omega$			3	ns

© Input and output frequency of ratings: 100MHz

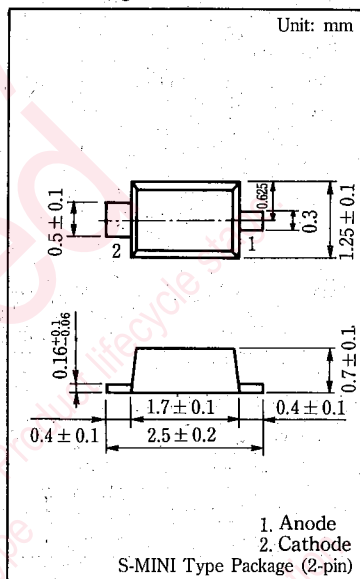
* t_{rr} measuring circuit



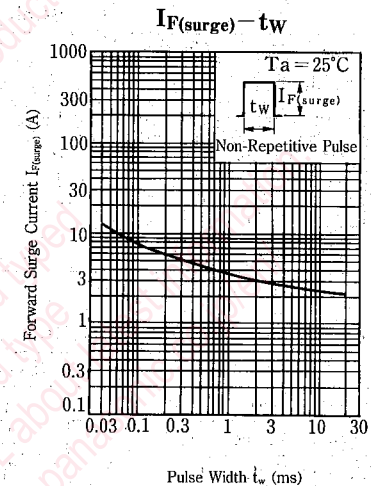
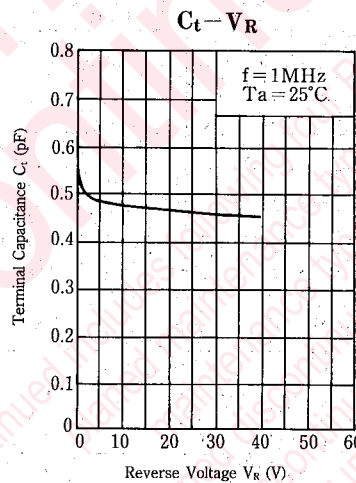
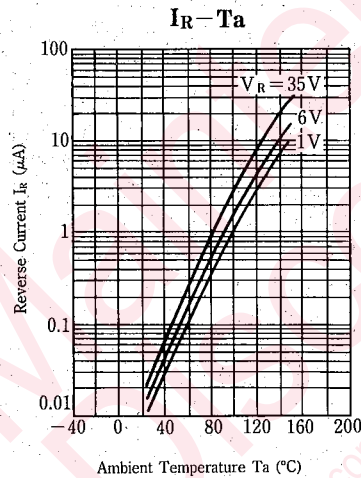
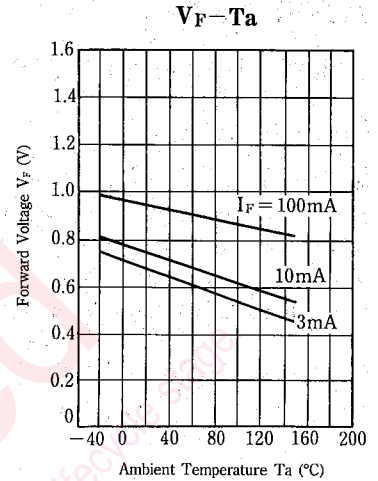
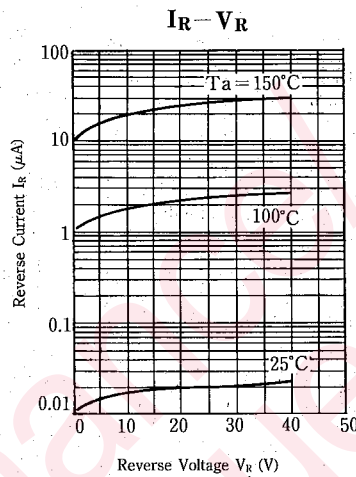
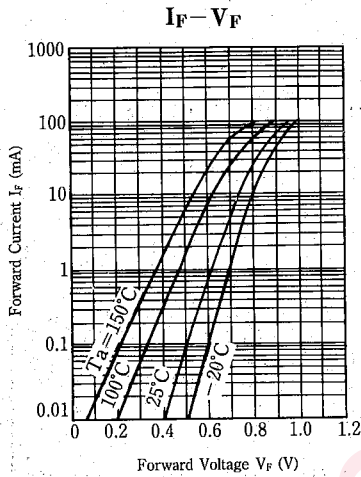
■ Marking Symbol



■ Package Dimensions



Marking Symbol : 1A



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